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(54) Title: METHODS OF PROCESSING A SUBSTRATE ON A BONDING SYSTEM, AND RELATED BONDING SYSTEMS

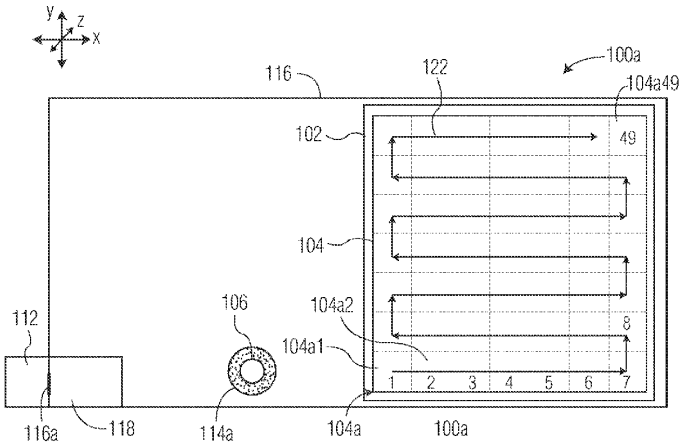


FIG. 5A

(57) Abstract: A method of processing a substrate on a bonding system is provided. The method includes: (a) providing an oxide reduction delivery system on a bonding system; (b) supporting a substrate on a support structure of the bonding system; and (c) moving at least one of the oxide reduction delivery system and the support structure with respect to one another, such that a gas provided by the oxide reduction delivery system contacts the substrate.

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